



# ORIENT

## Photo coupler

### Product DataSheet

MPN: OR-3H4 series

Customer: \_\_\_\_\_

Date: \_\_\_\_\_

**SHENZHEN ORIENT COMPONENTS CO.,LTD.**

Block A 3rd Floor No.4 Building, Tian'an Cyber Park, Huangge Rd, LongGang Dist, Shenzhen, GD

TEL: 0755-29681816

FAX: 075529681200

[www.orient-opto.com](http://www.orient-opto.com)

**Preliminary**

This datasheet is a preliminary design specification, and the formal specifications are subject to the recognition letter with jointly signed

## 1. Features

- (1) Current transfer ratio : MIN. 20% at  $I_F = \pm 1\text{mA}$ ,  $V_{CE} = 5\text{V}$ ,  $T_a = 25^\circ\text{C}$
- (2) High input-output isolation voltage.(VISO=3,750Vrms)
- (3)  $BV_{CEO} = 80\text{V(MIN)}$
- (4) Operating temperature:-55°C to 110°C
- (5) ESD pass HBM 8000V/MM 2000V
- (6) Safety approval
  - UL approved(No.E323844)
  - VDE approved(No.40029733)
  - CQC approved (No.CQC19001231256)
- (7) In compliance with RoHS, REACH standards
- (8) MSL Class I



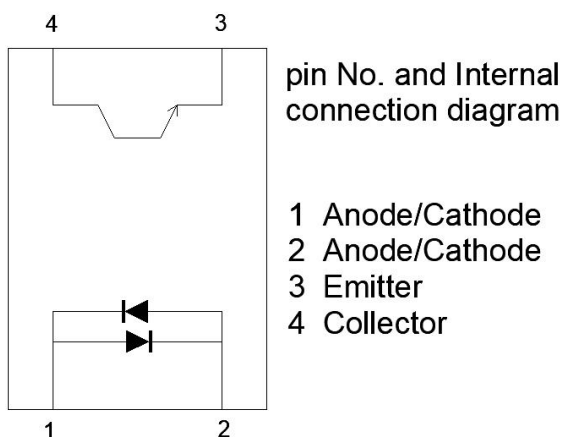
## 2. Instructions

The OR-3H4 series device contains two infrared led and a photo transistor detector.They are encapsulated in a 4-pin SSOP, free of halogens and Sb2O3

## 3. Application Range

- (1) Hybrid substrates that require high density mounting
- (2) Programmable controller
- (3) System apparatus,measuring instruments

## 4. Functional Diagram



**5. Max Absolute rated Value (Normal Temperature=25°C)**

Parameter		Symbol	Rated Value	Unit
Input	Forward Current	$I_F$	50	mA
	Peak forward Current (100μs pulse, 100Hz frequency)	$I_{FM}$	1	A
	Reverse Voltage	$V_R$	6	V
	Power Dissipation	P	65	mW
	Junction Temperature	$T_j$	125	°C
Output	Collector and emitter Voltage	$V_{CEO}$	80	V
	Emitter and collector Voltage	$V_{ECO}$	7	
	Collector Current	$I_C$	50	mA
	Power Dissipation	$P_C$	150	mW
	Junction Temperature	$T_j$	125	°C
Total Power Dissipation		$P_{tot}$	200	mW
*1 Insulation Voltage		$V_{iso}$	3750	Vrms
Operating Temperature		$T_{opr}$	-55 to +110	°C
Storage Temperature		$T_{stg}$	-55 to +125	
*2 Soldering Temperature		$T_{sol}$	260	

\*1. AC For 1 Minute, R.H. = 40 ~ 60%

Isolation voltage shall be measured using the following method.

- (1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side.
- (2) The isolation voltage tester with zero-cross circuit shall be used.
- (3) The waveform of applied voltage shall be a sine wave.

\*2.soldering time is 10 seconds.

**6. Opto-electronic Characteristics(Normal Temperature=25°C)**

Parameter		Symbol	Min	Typ.*	Max	Unit	Condition
Input	Forward Voltage	$V_F$	---	1.2	1.4	V	$I_F=\pm 20\text{mA}$
	Terminal capacitance	$C_t$	---	60	---	pF	$V=0, f=1\text{KHz}$
Output	Collector Dark Current	$I_{CEO}$	---	---	100	nA	$V_{CE}=20\text{V}, I_F=0\text{mA}$
	Collector and Emitter Breakdown Voltage	$BV_{CEO}$	80	---	---	V	$I_C=0.1\text{mA}, I_F=0\text{mA}$
	Emitter and Collector Breakdown Voltage	$BV_{ECO}$	7	---	---	V	$I_E=0.1\text{mA}, I_F=0\text{mA}$
	*1 Current Transfer Ratio	CTR	20	---	400	%	$I_F=\pm 1\text{mA}$ $V_{CE}=5\text{V}$
	Collector Current	$I_C$	0.2	---	4	mA	
Transforming Characteristics	Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	---	---	0.3	V	$I_F=\pm 8\text{mA}$ $I_C=2.4\text{mA}$
	Insulation Impedance	$R_{iso}$	$5 \times 10^{10}$	$1 \times 10^{11}$	---	$\Omega$	DC500V 40~60%R.H.
	Floating Capacitance	$C_f$	---	0.8	1	pF	$V=0, f=1\text{MHz}$
	Rise Time	$t_r$	---	3	18	$\mu\text{s}$	$V_{CE}=10\text{V}$ $I_C=2\text{mA}$ $R_L=100\Omega$
	Fall Time	$t_f$	---	4	18	$\mu\text{s}$	

- Current Conversion Ratio =  $I_C / I_F \times 100\%$

## 7. Rank table of current transfer ratio CTR

CTR Rank	Min.	Max.	Condition	Unit
NO mark	20	400	IF=±1mA, V <sub>CE</sub> =5V, Ta=25°C	%
A	50	250		
B	100	400		
C	100	200		
GR	100	300	IF=±5mA, V <sub>CE</sub> =5V, Ta=25°C	

- Current Conversion Ratio =  $I_C / I_F \times 100\%$

## 8. Order Information

### Part Number

**OR-3H4W-X-Y-Z**

### Note

W = CTR Rank (A, B, C, GR or none)

X = Tape and reel option (TP or TP1).

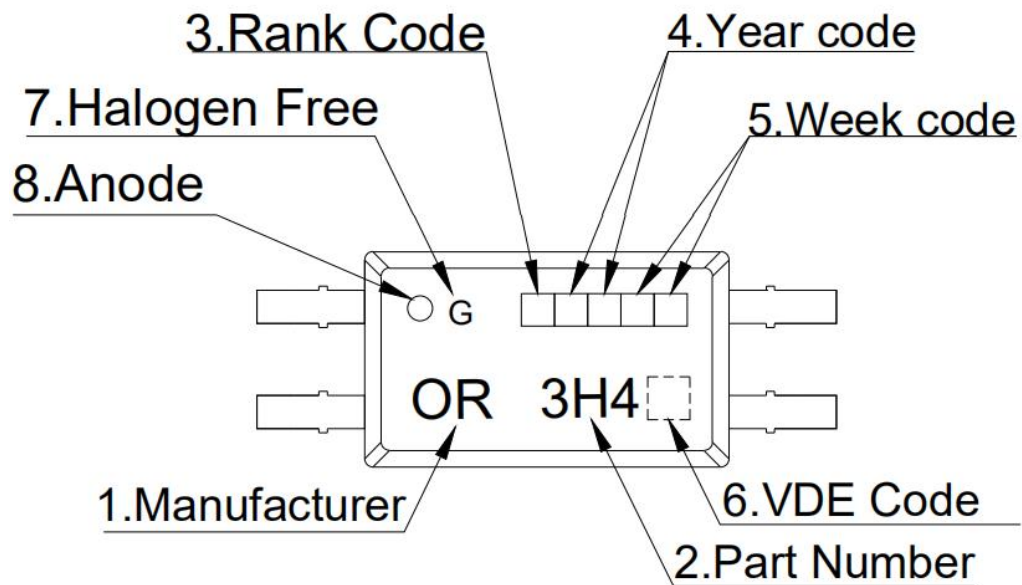
Y = 'V' code for VDE safety (This options is not necessary).

Z = 'G' code for Halogen free.

\* VDE Code can be selected.

Option	Description	Packing quantity
TP	Surface mount lead form (low profile) + TP tape & reel option	3000 units per reel
TP1	Surface mount lead form (low profile) + TP1 tape & reel option	3000 units per reel

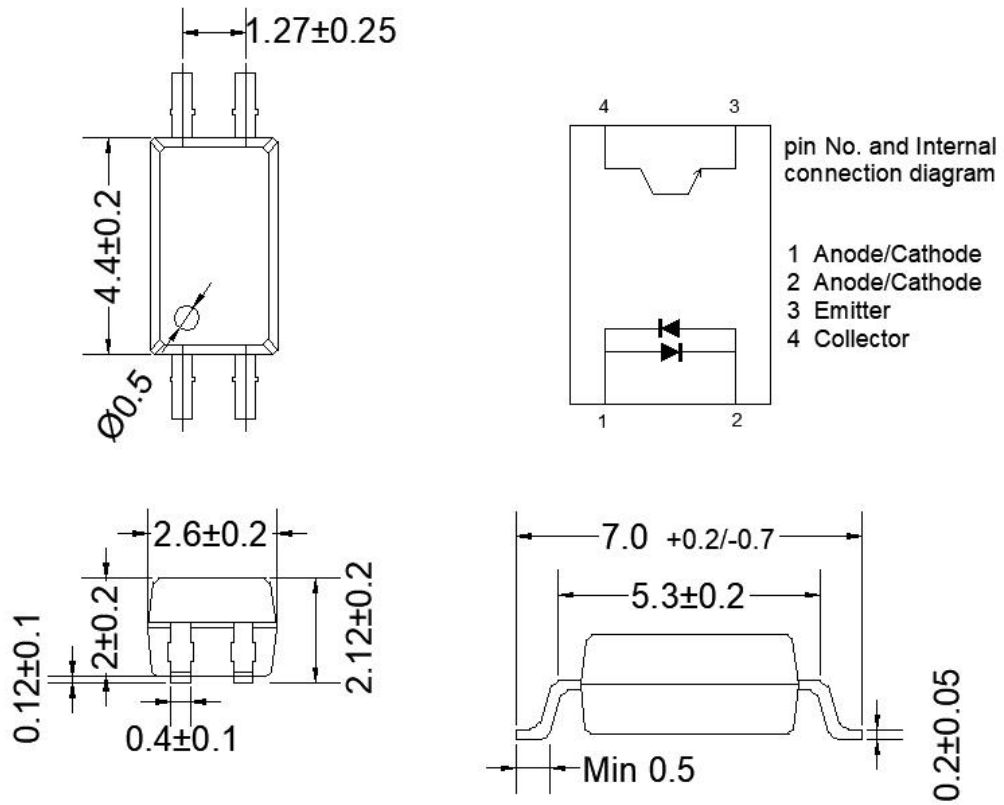
## 9. Naming Rule



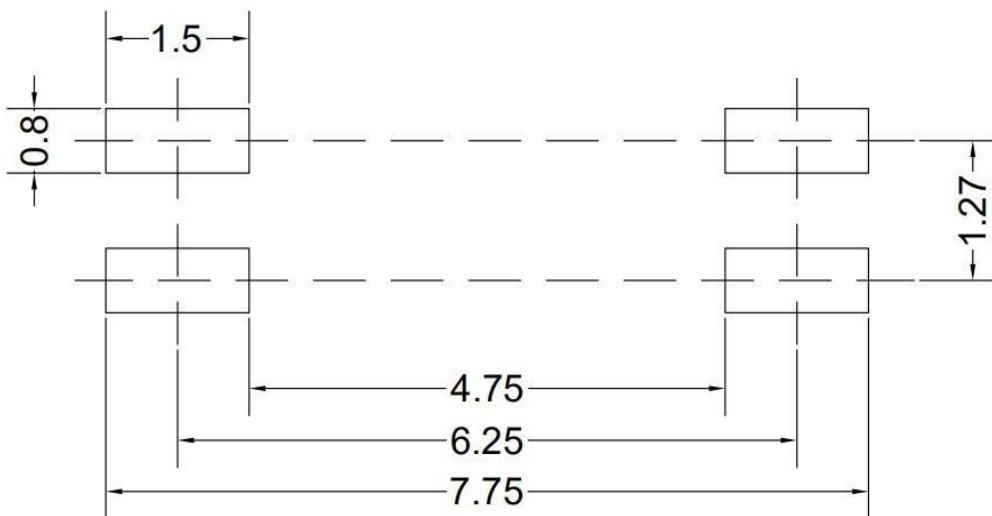
1. Manufacturer : ORIENT.
2. Part Number : 3H4.
3. Rank Code  : CTR Rank
4. Year Code  : '0' means '2020' and so on.
5. Week Code  : 01 means the first week, 02 means the second week and so on.
6. VDE Code . (Optional)
7. HF Code 'G': Halogen Free.
8. Anode.

\* VDE Code can be selected.

### 10. Outer Dimension

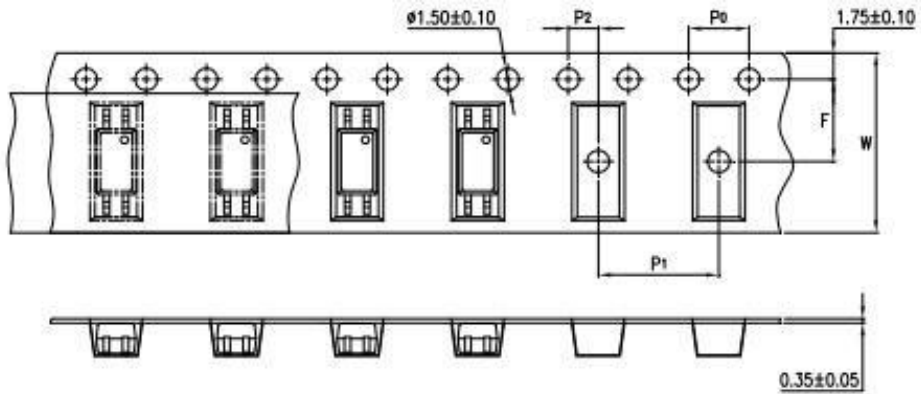


### 11. Recommended Foot Print Patterns (Mount Pad) (unit: mm)

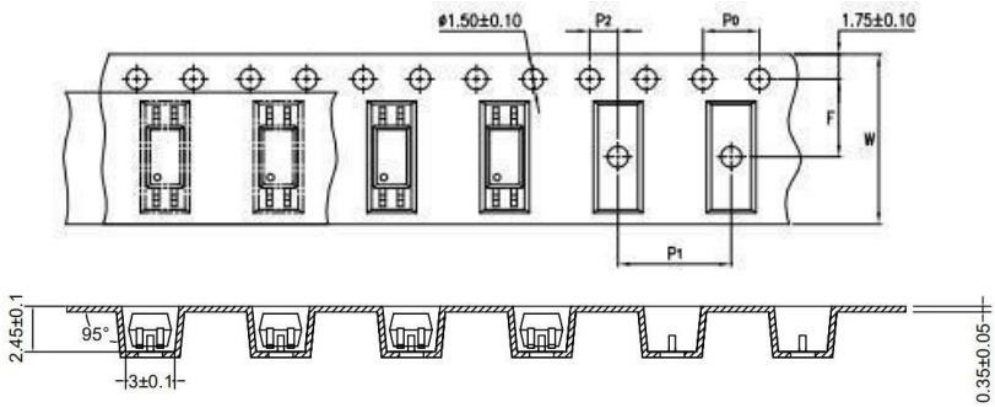


## 12. Taping Dimensions

### (1)OR-3H4-TP



### (2)OR-3H4-TP1



type	Symbol	Dimensions: mm (in.)
bandwidth	W	12±0.3 (0.47)
pitch	P0	4±0.1 (0.15)
pitch	F	5.5±0.1 (0.217)
	P2	2±0.1 (0.079)
interval	P1	8±0.1 (0.315)

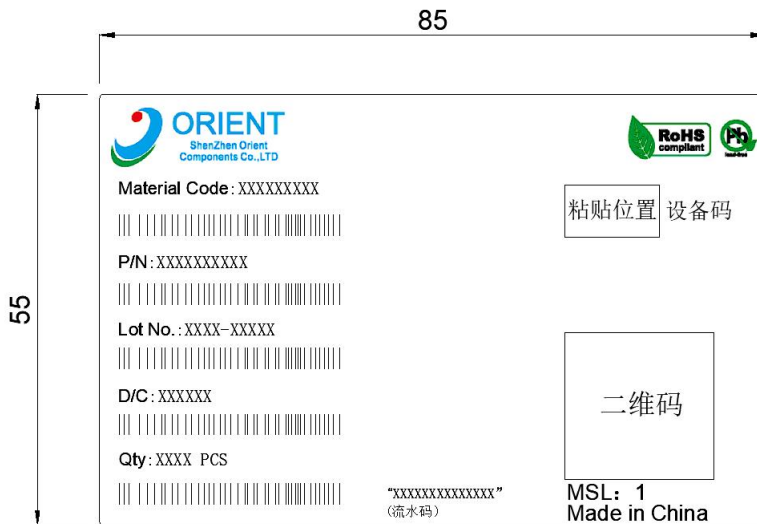
Encapsulation type	TP/TP1
Quantity (pieces)	3000

### 13. Package Dimension

#### (1) package dimension

Packing Information	
Packing type	Reel type
Tape Width	12mm
Qty per Reel	3,000pcs
Small box (inner) Dimension	345*345*45mm
Large box (Outer) Dimension	480x360x360mm
Max qty per small box	6,000pcs
Max qty per large box	60,000pcs

#### (2)Packing Label Sample



**Note :**

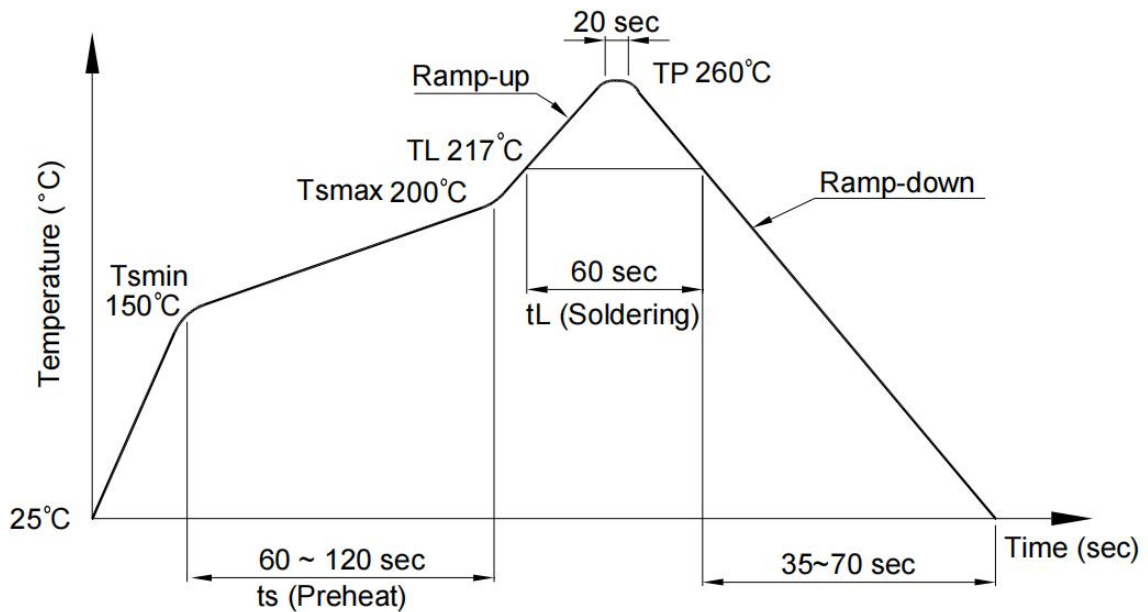
1. Material Code :Product ID.
2. P/N :Contents with "Order Information" in the specification.
3. Lot No. :Product weeks.
4. D/C :Product data.
5. Quantity :Packaging quantity.

## 14. Temperature Profile Of Soldering

### (1) IR Reflow soldering (JEDEC-STD-020 compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

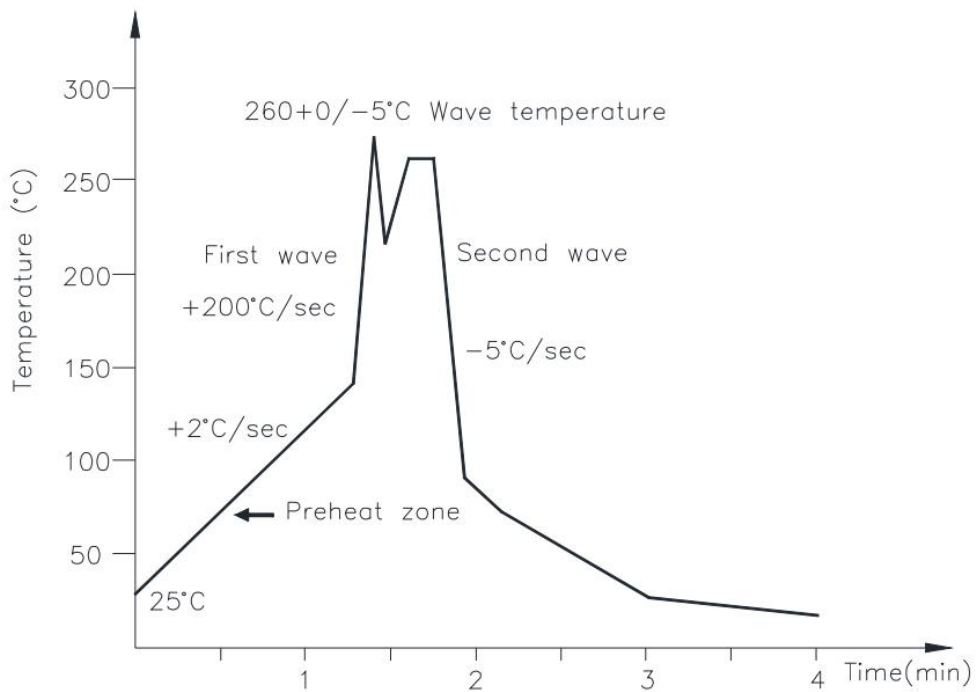
Profile item	Conditions
Preheat	
- Temperature Min (T Smin )	150°C
- Temperature Max (T Smax )	200°C
- Time (min to max) (ts)	90±30 sec
Soldering zone	
- Temperature (TL )	217°C
- Time (t L )	60 sec
Peak Temperature	260°C
Peak Temperature time	20 sec
Ramp-up rate	3°C / sec max.
Ramp-down rate from peak temperature	3~6°C / sec
Reflow times	≤3



**(2) Wave soldering (JEDEC22 A111 compliant)**

One time soldering is recommended within the condition of temperature.

Temperature	260+0/-5°C
Time	10 sec
Preheat temperature	25 to 140°C
Preheat time	30 to 80 sec



**(3) Hand soldering by soldering iron**

Allow single lead soldering in every single process. One time soldering is recommended.

Temperature	380+0/-5°C
Time	3 sec max

### 15. Characteristics Curves

Fig.1 Forward current vs Ambient temperature

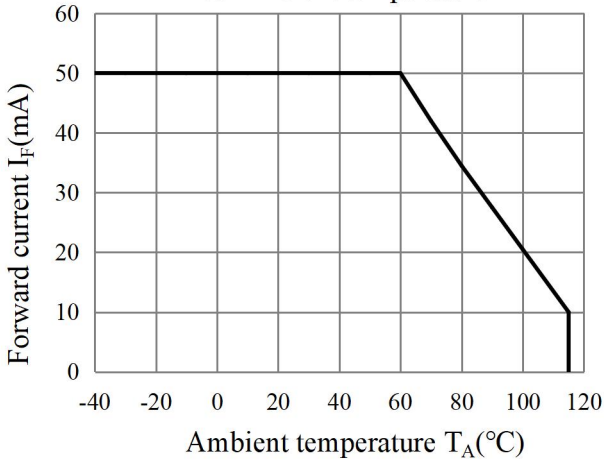


Fig.2 Collector Power Dissipation vs. Ambient temperature

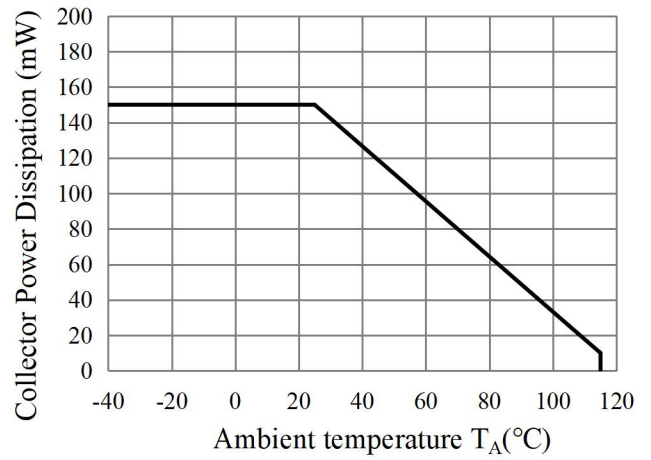


Fig.3 Forward Current vs. Forward Voltage

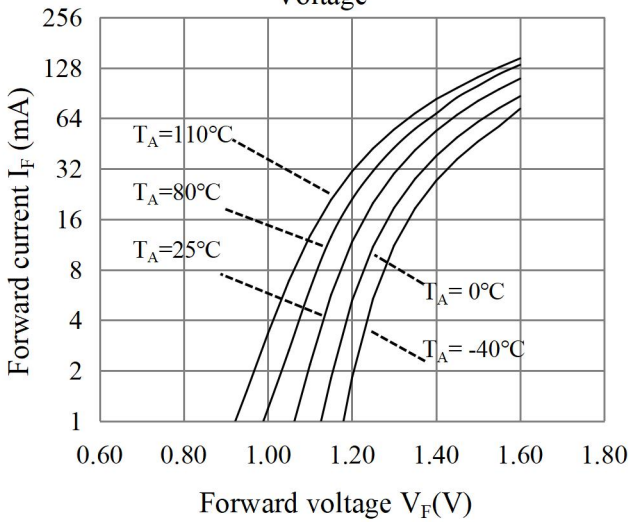


Fig.4 Collector-emitter Saturation Voltage vs. Forward Current

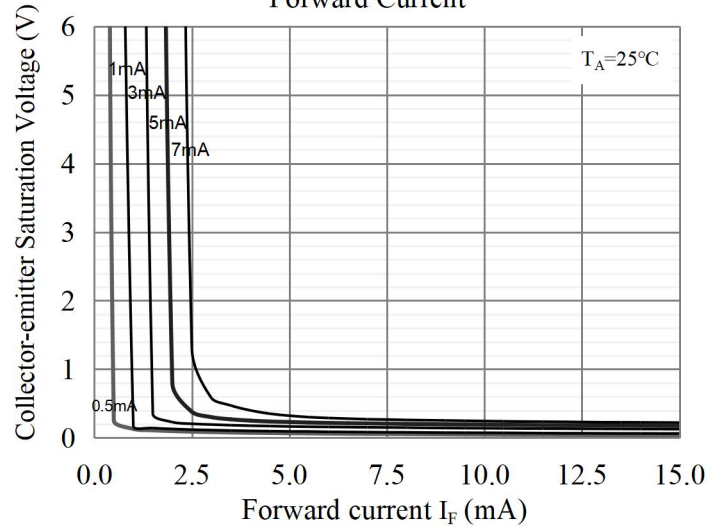


fig.5 Collector Current vs. Non-Saturated Collector Emitter Voltage

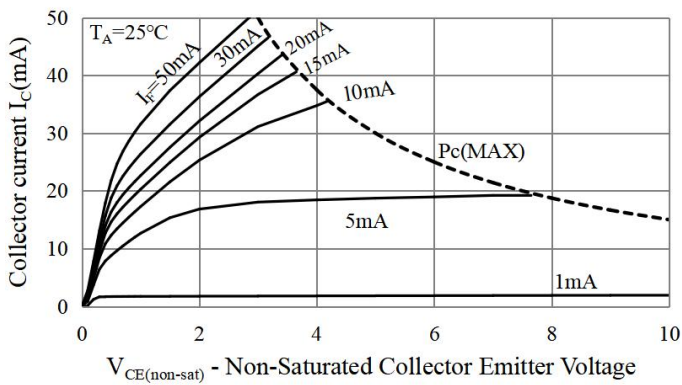


fig.6 Collector Current vs. Non-Saturated Collector Emitter Voltage

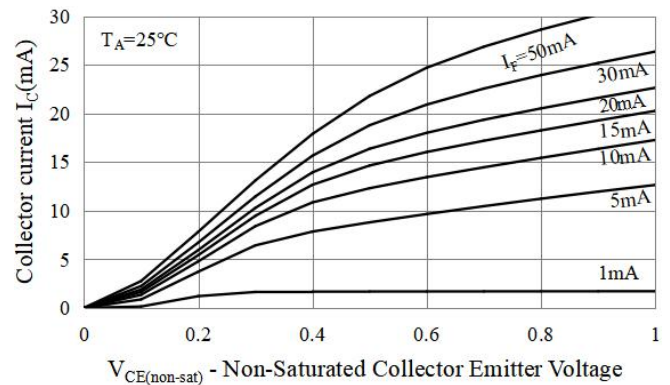


Fig.7 Relative Current Transfer Ratio vs. Ambient Temperature

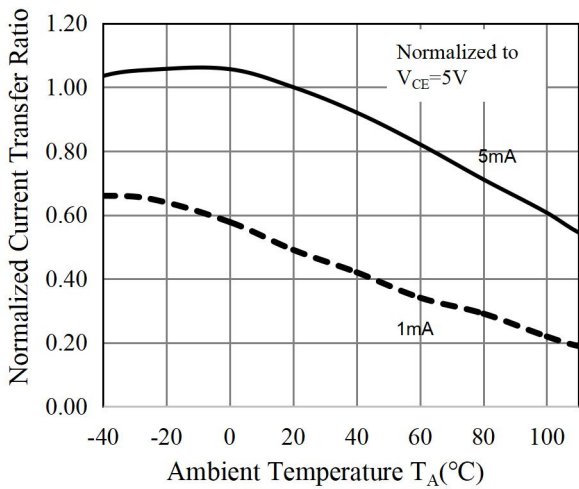


Fig.8 Relative Current Transfer Ratio vs. Ambient Temperature

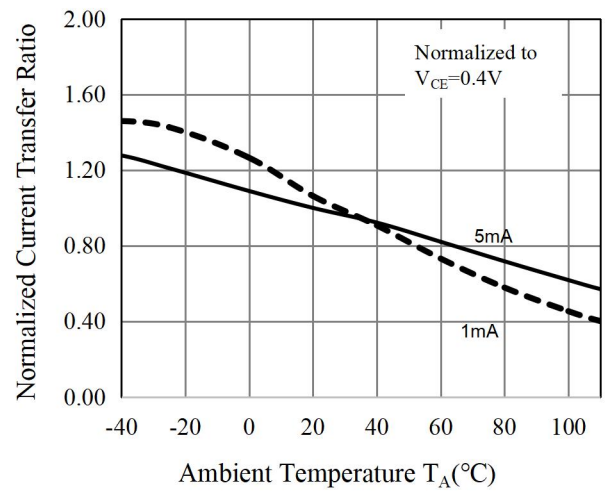


Fig.9 Forward Current vs. Current Transfer Ratio

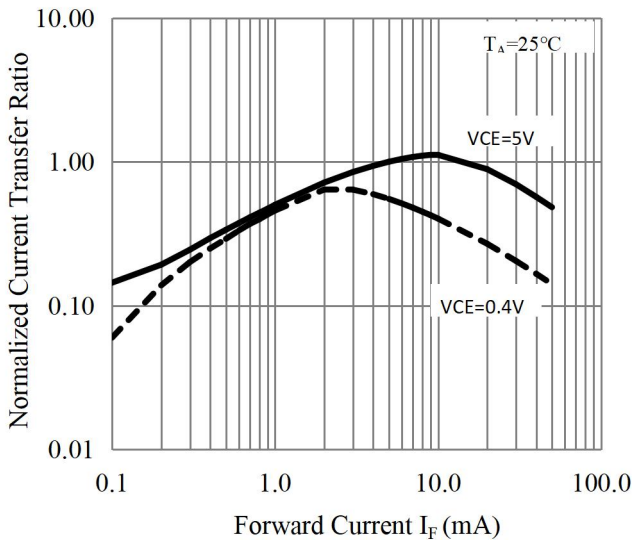


Fig.10 Collector Dark Current vs. Ambient Temperature

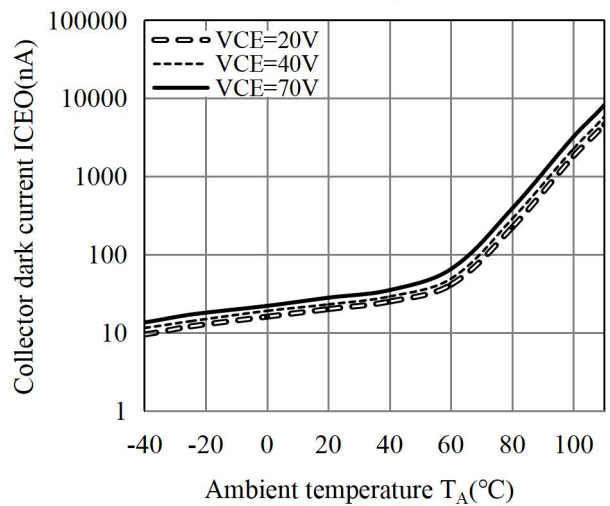


Fig.11 Collector-emitter Saturation Voltage vs. Ambient Temperature

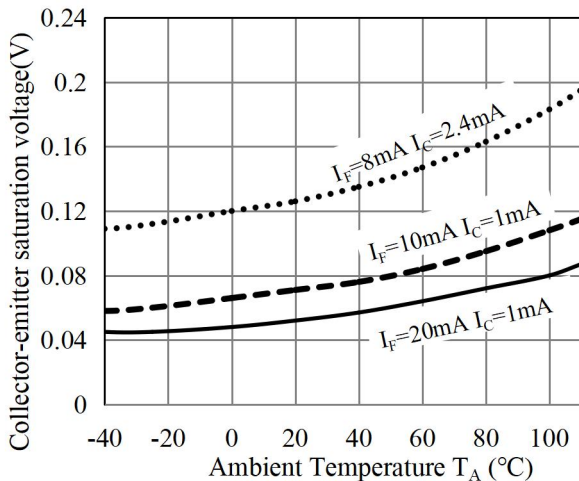


Fig.12 Switching Time vs. Load Resistance

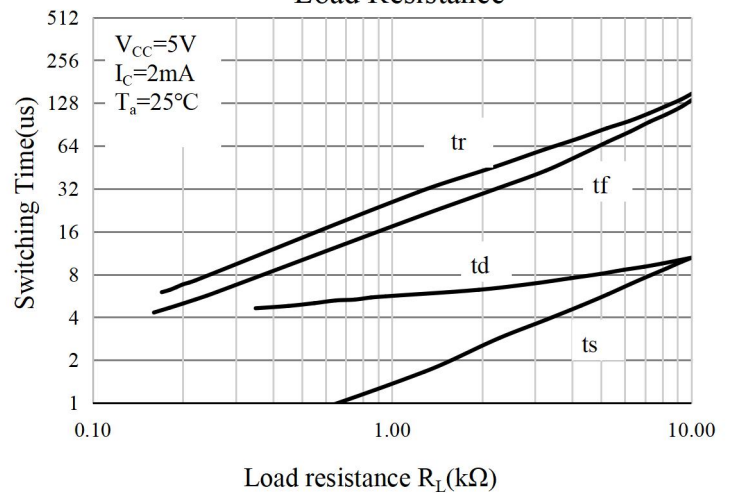


Fig.13 Respinse Time vs. Ambient temperature

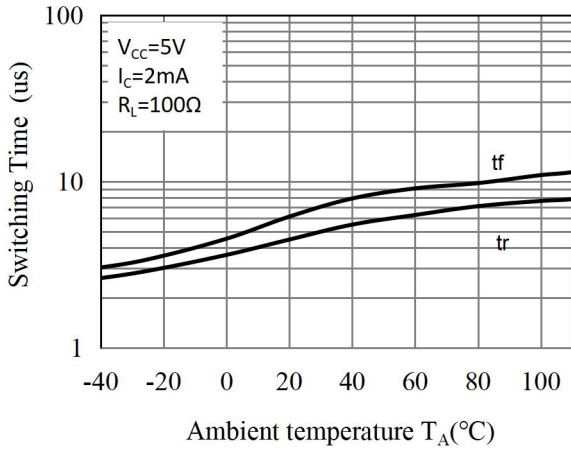
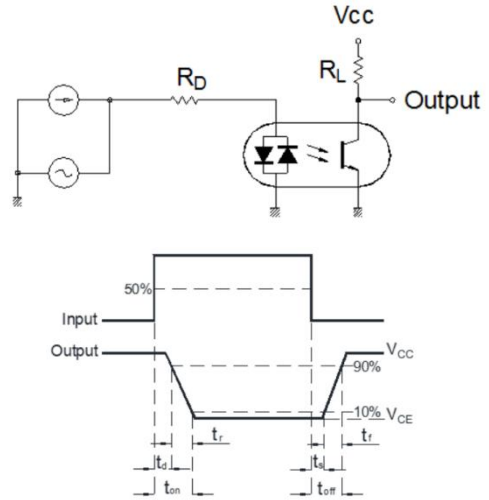


Fig.14 Switching Time Test Circuit & Waveforms



## 16. NOTES

1. Orient is continually improving the quality, reliability, function or design and Orient reserves the right to make changes without further notices.
2. The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
3. For equipment/devices where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc, please contact our sales representatives.
4. When requiring a device for any "specific" application, please contact our sales in advice.
5. If there are any questions about the contents of this publication, please contact us at your convenience.
6. The contents described herein are subject to change without prior notice.
7. Immerse unit's body in solder paste is not recommended.